

“All of our efforts on [the First World Congress on Integrated Computational Materials Engineering] should result in it being a “gold standard” international conference for years to come.”

— George Spanos

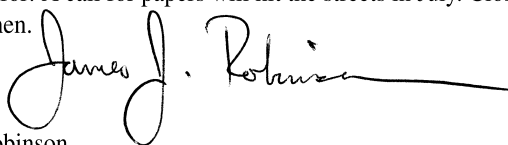
Those of you who are close followers of TMS know that society headquarters recently welcomed a new staff member: George Spanos, a well-known and much accomplished member of the materials community who comes to staff after a long stint at the U.S. Naval Research Laboratory. I must say that George is a nice guy, and I'm sure that all of staff will enjoy and benefit from working with him. Nice as George is, however, today's goal is not to sing George's praises. Instead, it is to sing the praises of one of the projects on which George is focusing much of his attention as a new staffer.

Strategically, George is busily at work leveraging his technical strengths in pursuit of key growth areas targeted by the TMS Board of Directors. One of those growth areas, close followers know, is to further develop the society's role as a leader in computational materials science and engineering. This just happens to be an area in which George has been strongly involved. Nearing the 30-year member mark, George has been an active volunteer in the society for some time, with his most recent pre-staff-member initiatives being affiliation with the new Integrated Computational Materials Engineering Committee and collaboration with his TMS partners Peter Collins (Quad Cities Manufacturing Lab) and John Allison (Ford Motor Company and TMS past president) to build the wire frame for the First World Congress on Integrated Computational Materials Engineering. The work of these three in conjunction with their extended networks of colleagues and general passion for the field is generating a lot of early excitement and enthusiasm for the realization of their collective vision. The meeting will be a big deal, reflecting and helping to better define a dawning materials community. The TMS Board of Directors certainly liked the organizers' plan for conducting a conference—they unanimously approving the meeting proposal in early June, just a few days after receiving it. It seems that they think it will be a model of success (pun intended).

So, what's all of the excitement about? Let me tease you with a few details:

- The meeting organizers are taking heavy doses of inspiration from the fabled Gordon Research Conference series, both in terms of networking-friendly scheduling and bucolic setting. Afternoons, for example, will be open so that attendees might interact in an unstructured environment.
- The location will be Seven Springs, Pennsylvania—home of the much-loved Superalloys conference series.
- The organizers are working to develop a program that models a robust and integrated profile of the ICME community. Check out the session themes: modeling processing-microstructure relationships; modeling microstructure-property relationships; ICME in education; information infrastructure; and success stories. That's a marvelous collection of cross-cutting interests and relationships with real-world grounding.
- The conference's International Advisory Committee has global representation (e.g., U.S., U.K., Brazil, Japan, Australia, Sweden, New Zealand, Germany, India, China, Korea, Denmark), pulling members from industry, government labs, and academia.
- A number of the biggest names in the field have agreed to be keynote speakers. (Can't say who, however, until the official publicity is released. Sorry.)
- A date worth saving: July 10–14, 2011. Exactly one year from this journal's date of publication (and a month in which *JOM* will examine the theme Modeling, Characterization, and Validation, interestingly enough).

Is there anything else exciting to say about the conference? Just one more thing that I have space for: A call for papers will hit the streets in July. Close followers will be the first to know when.



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